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Details	
Product Status	Active
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	271
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	324-LBGA
Supplier Device Package	324-FTBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-4ftn324c

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MachXO Family Data Sheet Architecture

June 2013 Data Sheet DS1002

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag "hard" control logic to minimize LUT use.

The MachXO registers in PFU and sysl/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

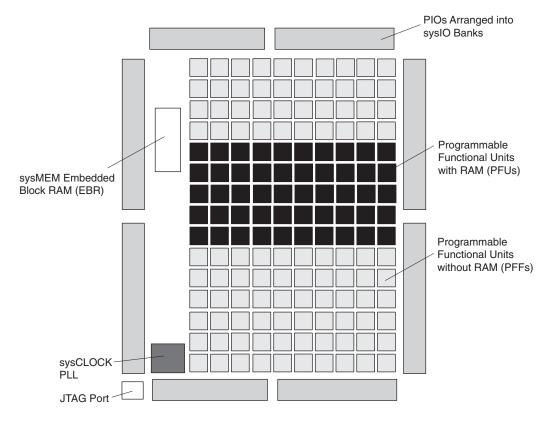
The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

www.latticesemi.com 2-1 DS1002 Architecture_01.5



Figure 2-1. Top View of the MachXO1200 Device¹



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

Figure 2-2. Top View of the MachXO640 Device

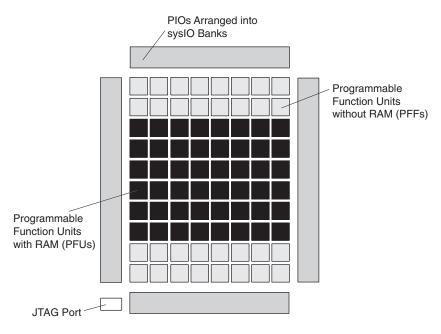
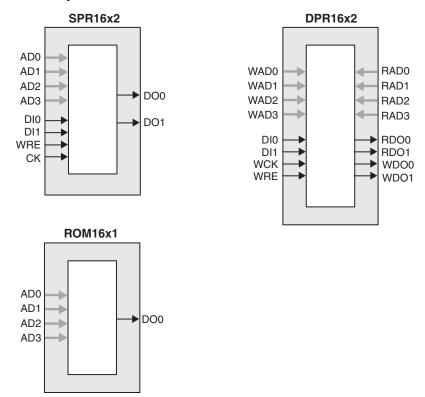




Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.



The EBR memory supports three forms of write behavior for single or dual port operation:

- 1. **Normal** data on the output appears only during the read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
- 2. **Write Through** a copy of the input data appears at the output of the same port. This mode is supported for all data widths.
- 3. **Read-Before-Write** when new data is being written, the old contents of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

FIFO Configuration

The FIFO has a write port with Data-in, CEW, WE and CLKW signals. There is a separate read port with Data-out, RCE, RE and CLKR signals. The FIFO internally generates Almost Full, Full, Almost Empty and Empty Flags. The Full and Almost Full flags are registered with CLKW. The Empty and Almost Empty flags are registered with CLKR. The range of programming values for these flags are in Table 2-7.

Table 2-7. Programmable FIFO Flag Ranges

Flag Name	Programming Range
Full (FF)	1 to (up to 2 ^N -1)
Almost Full (AF)	1 to Full-1
Almost Empty (AE)	1 to Full-1
Empty (EF)	0

N = Address bit width

The FIFO state machine supports two types of reset signals: RSTA and RSTB. The RSTA signal is a global reset that clears the contents of the FIFO by resetting the read/write pointer and puts the FIFO flags in their initial reset state. The RSTB signal is used to reset the read pointer. The purpose of this reset is to retransmit the data that is in the FIFO. In these applications it is important to keep careful track of when a packet is written into or read from the FIFO.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-13.



of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as "true" and "comp", where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will maintain the blank configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.



Figure 2-20. MachXO640 Banks

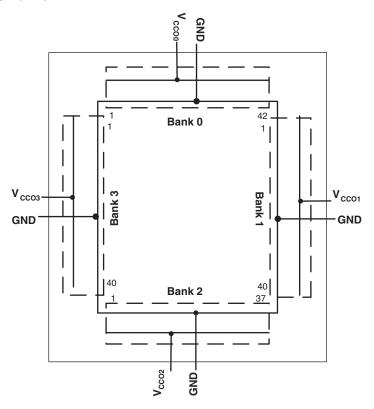
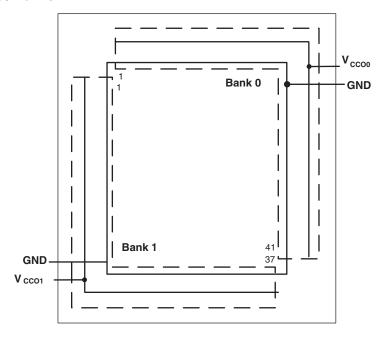


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of



Initialization Supply Current^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
		LCMXO256C	13	mA
		LCMXO640C	17	mA
		LCMXO1200C	21	mA
,	Core Power Supply	LCMXO2280C	23	mA
Icc	Core Fower Supply	LCMXO256E	10	mA
		LCMXO640E	14	mA
		LCMXO1200E	18	mA
		LCMXO2280E	20	mA
		LCMXO256E/C	10	mA
1	Auxiliary Power Supply	LCMXO640E/C	13	mA
ICCAUX	$V_{CCAUX} = 3.3V$	LCMXO1200E/C	24	mA
		LCMXO2280E/C	25	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	2	mA

- 1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
- 2. Assumes all I/O pins are held at V_{CCIO} or GND.
- 3. Frequency = 0MHz.
- 4. Typical user pattern.
- 5. $T_J = 25^{\circ}C$, power supplies at nominal voltage.
- 6. Per Bank, V_{CCIO} = 2.5V. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current^{1, 2, 3, 4}

Symbol	Parameter	Device	Typ.⁵	Units
		LCMXO256C	9	mA
		LCMXO640C	11	mA
		LCMXO1200C	16	mA
	Core Power Supply	LCMXO2280C	22	mA
Icc	Core Fower Supply	LCMXO256E	6	mA
		LCMXO640E	8	mA
		LCMXO1200E	12	mA
		LCMXO2280E	14	mA
		LCMXO256C/E	8	mA
1	Auxiliary Power Supply	LCMXO640C/E	10	mA
CCAUX	$V_{CCAUX} = 3.3V$	LCMXO1200/E	15	mA
		LCMXO2280C/E	16	mA
I _{CCIO}	Bank Power Supply ⁶	All devices	2	mA

- 1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
- 2. Assumes all I/O pins are held at V_{CCIO} or GND.
- 3. Typical user pattern.
- 4. JTAG programming is at 25MHz.
- 5. $T_J = 25$ °C, power supplies at nominal voltage.
- 6. Per Bank. V_{CCIO} = 2.5V. Does not include pull-up/pull-down.



Table 3-1. LVDS DC Conditions

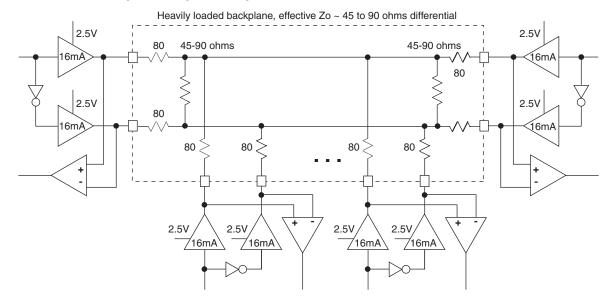
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	Ω
R _S	Driver series resistor	294	Ω
R _P	Driver parallel resistor	121	Ω
R _T	Receiver termination	100	Ω
V _{OH}	Output high voltage	1.43	V
V _{OL}	Output low voltage	1.07	V
V _{OD}	Output differential voltage	0.35	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	100	Ω
I _{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example





For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

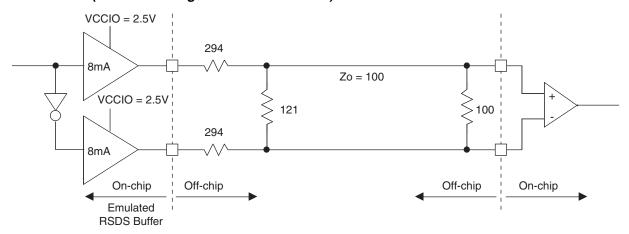


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	Ohms
R _S	Driver series resistor	294	Ohms
R _P	Driver parallel resistor	121	Ohms
R _T	Receiver termination	100	Ohms
V _{OH}	Output high voltage	1.35	V
V _{OL}	Output low voltage	1.15	V
V _{OD}	Output differential voltage	0.20	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	101.5	Ohms
I _{DC}	DC output current	3.66	mA



Power Supply and NC

Signal	100 TQFP ¹	144 TQFP ¹	100 csBGA ²
VCC	LCMXO256/640: 35, 90 LCMXO1200/2280: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	LCMXO256: 60, 74, 92 LCMXO640: 80, 92 LCMXO1200/2280: 94	LCMXO640: 117, 135 LCMXO1200/2280: 135	LCMXO256: H14, A14, B5 LCMXO640: B12, B5
VCCIO1	LCMXO256: 10, 24, 41 LCMXO640: 60, 74 LCMXO1200/2280: 80	LCMXO640: 82, 98 LCMXO1200/2280: 117	LCMXO256: G1, P1, P10 LCMXO640: H14, A14
VCCIO2	LCMXO256: None LCMXO640: 29, 41 LCMXO1200/2280: 70	LCMXO640: 38, 63 LCMXO1200/2280: 98	LCMXO256: None LCMXO640: P4, P10
VCCIO3	LCMXO256: None LCMXO640: 10, 24 LCMXO1200/2280: 56	LCMXO640: 10, 26 LCMXO1200/2280: 82	LCMXO256: None LCMXO640: G1, P1
VCCIO4	LCMXO256/640: None LCMXO1200/2280: 44	LCMXO640: None LCMXO1200/2280: 63	_
VCCIO5	LCMXO256/640: None LCMXO1200/2280: 27	LCMXO640: None LCMXO1200/2280: 38	_
VCCIO6	LCMXO256/640: None LCMXO1200/2280: 20	LCMXO640: None LCMXO1200/2280: 26	_
VCCIO7	LCMXO256/640: None LCMXO1200/2280: 6	LCMXO640: None LCMXO1200/2280: 10	_
VCCAUX	LCMXO256/640: 88 LCMXO1200/2280: 36, 90	53, 128	B7
GND ³	LCMXO256: 40, 84, 62, 75, 93, 12, 25, 42 LCMXO640: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 LCMXO1200/2280: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	LCMXO256: N9, B9, G14, B13, A4, H1, N2, N10 LCMXO640: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC ⁴			_

Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
NC pins should not be connected to any active signals, VCC or GND.



Power Supply and NC (Cont.)

Signal	132 csBGA¹	256 caBGA / 256 ftBGA ¹	324 ftBGA ¹
VCC	H3, P6, G12, C7	G7, G10, K7, K10	F14, G11, G9, H7, L7, M9
VCCIO0	LCMXO640: B11, C5 LCMXO1200/2280: C5	LCMXO640: F8, F7, F9, F10 LCMXO1200/2280: F8, F7	G8, G7
VCCIO1	LCMXO640: L12, E12 LCMXO1200/2280: B11	LCMXO640: H11, G11, K11, J11 LCMXO1200/2280: F9, F10	G12, G10
VCCIO2	LCMXO640: N2, M10 LCMXO1200/2280: E12	LCMXO640: L9, L10, L8, L7 LCMXO1200/2280: H11, G11	J12, H12
VCCIO3	LCMXO640: D2, K3 LCMXO1200/2280: L12	LCMXO640: K6, J6, H6, G6 LCMXO1200/2280: K11, J11	L12, K12
VCCIO4	LCMXO640: None LCMXO1200/2280: M10	LCMXO640: None LCMXO1200/2280: L9, L10	M12, M11
VCCIO5	LCMXO640: None LCMXO1200/2280: N2	LCMXO640: None LCMXO1200/2280: L8, L7	M8, R9
VCCIO6	LCMXO640: None LCMXO1200/2280: K3	LCMXO640: None LCMXO1200/2280: K6, J6	M7, K7
VCCIO7	LCMXO640: None LCMXO1200/2280: D2	LCMXO640: None LCMXO1200/2280: H6, G6	H6, J7
VCCAUX	P7, A7	T9, A8	M10, F9
GND ²	F1, P9, J14, C9, A10, B4, L13, D13, P2, N11, E1, L2	A1, A16, F11, G8, G9, H7, H8, H9, H10, J7, J8, J9, J10, K8, K9, L6, T1, T16	E14, F16, H10, H11, H8, H9, J10, J11, J4, J8, J9, K10, K11, K17, K8, K9, L10, L11, L8, L9, N2, P14, P5, R7
NC ³		LCMXO640: E4, E5, F5, F6, C3, C2, G4, G5, H4, H5, K5, K4, M5, M4, P2, P3, N5, N6, M7, M8, N10, N11, R15, R16, P15, P16, M11, L11, N12, N13, M13, M12, K12, J12, F12, F13, E12, E13, D13, D14, B15, A15, C14, B14, E11, E10, E7, E6, D4, D3, B3, B2 LCMXO1200: None LCMXO2280: None	

Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
NC pins should not be connected to any active signals, VCC or GND.



LCMXO256 and LCMXO640 Logic Signal Connections: 100 TQFP (Cont.)

		LCMX	(O256		LCMXO640			
Pin Number	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
43	PB4A	1		Т	PB8B	2		
44	PB4B	1		С	PB8C	2		Т
45	PB4C	1		Т	PB8D	2		С
46	PB4D	1		С	PB9A	2		
47	PB5A	1			PB9C	2		Т
48*	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
49	PB5C	1		Т	PB9D	2		С
50	PB5D	1		С	PB9F	2		
51	PR9B	0		С	PR11D	1		С
52	PR9A	0		Т	PR11B	1		С
53	PR8B	0		С	PR11C	1		Т
54	PR8A	0		Т	PR11A	1		Т
55	PR7D	0		С	PR10D	1		С
56	PR7C	0		Т	PR10C	1		Т
57	PR7B	0		С	PR10B	1		С
58	PR7A	0		Т	PR10A	1		Т
59	PR6B	0		С	PR9D	1		
60	VCCIO0	0			VCCIO1	1		
61	PR6A	0		Т	PR9B	1		
62	GNDIO0	0			GNDIO1	1		
63	PR5D	0		С	PR7B	1		
64	PR5C	0		Т	PR6C	1		
65	PR5B	0		С	PR6B	1		
66	PR5A	0		Т	PR5D	1		
67	PR4B	0		С	PR5B	1		
68	PR4A	0		Т	PR4D	1		
69	PR3D	0		С	PR4B	1		
70	PR3C	0		Т	PR3D	1		
71	PR3B	0		С	PR3B	1		
72	PR3A	0		Т	PR2D	1		
73	PR2B	0		С	PR2B	1		
74	VCCIO0	0			VCCIO1	1		
75	GNDIO0	0			GNDIO1	1		
76	PR2A	0		Т	PT9F	0		С
77	PT5C	0			PT9E	0		Т
78	PT5B	0		С	PT9C	0		
79	PT5A	0		Т	PT9A	0		
80	PT4F	0		С	VCCIO0	0		
81	PT4E	0		Т	GNDIO0	0		
82	PT4D	0		С	PT7E	0		
83	PT4C	0		Т	PT7A	0		
84	GND	-			GND	-		



LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA (Cont.)

		LCMXO256			LCMXO640				
Ball Number	Ball Function	Bank	Dual Function	Differen- tial	Ball Number	Ball Function	Bank	Dual Function	Differen- tial
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		Т	B4	PT3B	0		С
A3	PT2F	0		С	A3	PT3A	0		T
B3	PT2E	0		Т	B3	PT2F	0		С
A2	PT2D	0		С	A2	PT2E	0		T
C3	PT2C	0		Т	C3	PT2B	0		С
A1	PT2B	0		С	A1	PT2C	0		
B2	PT2A	0		Т	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

^{*}NC for "E" devices.

^{**}Primary clock inputs are single-ended.



LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

		L	CMXO640			LCMXO1200			LCMXO2280			
Pin Number	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		С	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		Т	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		С	PR3D	2		С	PR4D	2		С
104	PR2D	1		С	PR3C	2		Т	PR4C	2		Т
105	PR3A	1		Т	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		С	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		Т	PR2B	2		С	PR3B	2		C*
108	PR2A	1		Т	PR2A	2		Т	PR3A	2		T*
109	PT9F	0		С	PT11D	1		С	PT16D	1		С
110	PT9D	0		С	PT11C	1		T	PT16C	1		Т
111	PT9E	0		Т	PT11B	1		С	PT16B	1		С
112	PT9B	0		С	PT11A	1		T	PT16A	1		Т
113	PT9C	0		Т	PT10F	1		С	PT15D	1		С
114	PT9A	0		Т	PT10E	1		Т	PT15C	1		Т
115	PT8C	0			PT10D	1		С	PT14B	1		С
116	PT8B	0		С	PT10C	1		Т	PT14A	1		Т
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		Т	PT9F	1		С	PT12F	1		С
120	PT7E	0			PT9E	1		Т	PT12E	1		Т
121	PT7C	0			PT9B	1		С	PT12D	1		С
122	PT7A	0			PT9A	1		Т	PT12C	1		Т
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	С	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		Т	PT7B	1		С	PT9D	1		С
126	PT5C	0			PT7A	1		Т	PT9C	1		Т
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		С	PT7B	0		С
131	PT4B	0		С	PT5C	0		Т	PT7A	0		Т
132	PT4A	0		Т	PT5B	0		С	PT6D	0		
133	PT3F	0			PT5A	0		Т	PT6E	0		Т
134	PT3D	0			PT4B	0			PT6F	0		С
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		С	PT3D	0		С	PT4B	0		Т
138	PT2F	0		С	PT3C	0		Т	PT4A	0		С
139	PT3A	0		Т	PT3B	0		С	PT3B	0		С
140	PT2D	0		С	PT3A	0		Т	PT3A	0		Т
141	PT2E	0		Т	PT2D	0		С	PT2D	0		С
142	PT2B	0		С	PT2C	0		Т	PT2C	0		Т
143	PT2C	0		Т	PT2B	0		С	PT2B	0		С
144	PT2A	0		Т	PT2A	0		Т	PT2A	0		Т

^{*}Supports true LVDS outputs.

^{**}NC for "E" devices.

^{***}Primary clock inputs arer single-ended.



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280					
Ball Number	Ball Function	Bank	Dual Function	Differential	
G2	PL11A	6		T*	
H2	PL11B	6		C*	
L3	PL11C	6		Т	
L5	PL11D	6		С	
H1	PL12A	6		T*	
VCCIO6	VCCIO6	6			
GND	GNDIO6	6			
J2	PL12B	6		C*	
L4	PL12C	6		Т	
L6	PL12D	6		С	
K2	PL13A	6		T*	
K1	PL13B	6		C*	
J1	PL13C	6		Т	
VCC	VCC	-			
L2	PL13D	6		С	
M5	PL14D	6		С	
M3	PL14C	6	TSALL	Т	
L1	PL14B	6		C*	
M2	PL14A	6		T*	
M1	PL15A	6		T*	
N1	PL15B	6		C*	
M6	PL15C	6		Ŧ	
M4	PL15D	6		С	
VCCIO6	VCCIO6	6			
GND	GNDIO6	6			
P1	PL16A	6		T*	
P2	PL16B	6		C*	
N3	PL16C	6		Т	
N4	PL16D	6		С	
GND	GND	-			
T1	PL17A	6	LLM0_PLLT_FB_A	T*	
R1	PL17B	6	LLM0_PLLC_FB_A	C*	
P3	PL17C	6		Т	
N5	PL17D	6		С	
R3	PL18A	6	LLM0_PLLT_IN_A	T*	
R2	PL18B	6	LLM0_PLLC_IN_A	C*	
P4	PL19A	6		Т	
N6	PL19B	6		С	
U1	PL20A	6		Т	
VCCIO6	VCCIO6	6			
GND	GNDIO6	6			
GND	GNDIO5	5			
VCCIO5	VCCIO5	5			



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

	LCMXO2280					
Ball Number	Ball Function	Bank	Dual Function	Differential		
GND	GNDIO3	3				
VCCIO3	VCCIO3	3				
P15	PR20B	3		С		
N14	PR20A	3		Т		
N15	PR19B	3		С		
M13	PR19A	3		Т		
R15	PR18B	3		C*		
T16	PR18A	3		T*		
N16	PR17D	3		С		
M14	PR17C	3		Т		
U17	PR17B	3		C*		
VCC	VCC	-				
U18	PR17A	3		T*		
R17	PR16D	3		С		
R16	PR16C	3		Т		
P16	PR16B	3		C*		
VCCIO3	VCCIO3	3				
GND	GNDIO3	3				
P17	PR16A	3		T*		
L13	PR15D	3		С		
M15	PR15C	3		Т		
T17	PR15B	3		C*		
T18	PR15A	3		T*		
L14	PR14D	3		С		
L15	PR14C	3		T		
R18	PR14B	3		C*		
P18	PR14A	3		T*		
GND	GND	-				
K15	PR13D	3		С		
K13	PR13C	3		T		
N17	PR13B	3		C*		
N18	PR13A	3		T*		
K16	PR12D	3		С		
K14	PR12C	3		T		
M16	PR12B	3		C*		
L16	PR12A	3		T*		
GND	GNDIO3	3				
VCCIO3	VCCIO3	3				
J16	PR11D	3		С		
J14	PR11C	3		Т		
M17	PR11B	3		C*		
L17	PR11A	3		T*		
J15	PR10D	2		С		



LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

	LCMXO2280					
Ball Number	Ball Function	Bank	Dual Function	Differential		
J13	PR10C	2		Т		
M18	PR10B	2		C*		
L18	PR10A	2		T*		
GND	GNDIO2	2				
VCCIO2	VCCIO2	2				
H16	PR9D	2		С		
H14	PR9C	2		Т		
K18	PR9B	2		C*		
J18	PR9A	2		T*		
J17	PR8D	2		С		
VCC	VCC	-				
H18	PR8C	2		Т		
H17	PR8B	2		C*		
G17	PR8A	2		T*		
H13	PR7D	2		С		
H15	PR7C	2		T		
G18	PR7B	2		C*		
F18	PR7A	2		T*		
G14	PR6D	2		С		
G16	PR6C	2		Т		
VCCIO2	VCCIO2	2				
GND	GNDIO2	2				
E18	PR6B	2		C*		
F17	PR6A	2		T*		
G13	PR5D	2		С		
G15	PR5C	2		Т		
E17	PR5B	2		C*		
E16	PR5A	2		T*		
GND	GND	-				
F15	PR4D	2		С		
E15	PR4C	2		Т		
D17	PR4B	2		C*		
D18	PR4A	2		T*		
B18	PR3D	2		С		
C18	PR3C	2		T		
C16	PR3B	2		C*		
D16	PR3A	2		T*		
C17	PR2B	2		С		
D15	PR2A	2		T		
VCCIO2	VCCIO2	2				
GND	GNDIO2	2				
GND	GNDIO1	1				
VCCIO1	VCCIO1	1				



Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3TN100C	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO2280C-4TN100C	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO2280C-5TN100C	2280	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO2280C-3TN144C	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO2280C-4TN144C	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO2280C-5TN144C	2280	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO2280C-3MN132C	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO2280C-4MN132C	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO2280C-5MN132C	2280	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO2280C-3BN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO2280C-4BN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO2280C-5BN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO2280C-3FTN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO2280C-4FTN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO2280C-5FTN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM
LCMXO2280C-3FTN324C	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	COM
LCMXO2280C-4FTN324C	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	COM
LCMXO2280C-5FTN324C	2280	1.8V/2.5V/3.3V	271	-5	Lead-Free ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3TN100C	256	1.2V	78	-3	Lead-Free TQFP	100	COM
LCMXO256E-4TN100C	256	1.2V	78	-4	Lead-Free TQFP	100	COM
LCMXO256E-5TN100C	256	1.2V	78	-5	Lead-Free TQFP	100	COM
LCMXO256E-3MN100C	256	1.2V	78	-3	Lead-Free csBGA	100	COM
LCMXO256E-4MN100C	256	1.2V	78	-4	Lead-Free csBGA	100	COM
LCMXO256E-5MN100C	256	1.2V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3TN100C	640	1.2V	74	-3	Lead-Free TQFP	100	COM
LCMXO640E-4TN100C	640	1.2V	74	-4	Lead-Free TQFP	100	COM
LCMXO640E-5TN100C	640	1.2V	74	-5	Lead-Free TQFP	100	COM
LCMXO640E-3MN100C	640	1.2V	74	-3	Lead-Free csBGA	100	COM
LCMXO640E-4MN100C	640	1.2V	74	-4	Lead-Free csBGA	100	COM
LCMXO640E-5MN100C	640	1.2V	74	-5	Lead-Free csBGA	100	COM
LCMXO640E-3TN144C	640	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMXO640E-4TN144C	640	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMXO640E-5TN144C	640	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMXO640E-3MN132C	640	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMXO640E-4MN132C	640	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMXO640E-5MN132C	640	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMXO640E-3BN256C	640	1.2V	159	-3	Lead-Free caBGA	256	COM
LCMXO640E-4BN256C	640	1.2V	159	-4	Lead-Free caBGA	256	COM
LCMXO640E-5BN256C	640	1.2V	159	-5	Lead-Free caBGA	256	COM
LCMXO640E-3FTN256C	640	1.2V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640E-4FTN256C	640	1.2V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640E-5FTN256C	640	1.2V	159	-5	Lead-Free ftBGA	256	COM



Lead-Free Packaging

Industrial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	IND
LCMXO256C-4TN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	IND
LCMXO256C-3MN100I	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	IND
LCMXO256C-4MN100I	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	IND
LCMXO640C-4TN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	IND
LCMXO640C-3MN100I	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	IND
LCMXO640C-4MN100I	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	IND
LCMXO640C-3TN144I	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO640C-4TN144I	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO640C-3MN132I	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO640C-4MN132I	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO640C-3BN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	IND
LCMXO640C-4BN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	IND
LCMXO640C-3FTN256I	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	IND
LCMXO640C-4FTN256I	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100I	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMXO1200C-4TN100I	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMXO1200C-3TN144I	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO1200C-4TN144I	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO1200C-3MN132I	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO1200C-4MN132I	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO1200C-3BN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMXO1200C-4BN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMXO1200C-3FTN256I	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMXO1200C-4FTN256I	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280C-3TN100I	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	IND
LCMXO2280C-4TN100I	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	IND
LCMXO2280C-3TN144I	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	IND
LCMXO2280C-4TN144I	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	IND
LCMXO2280C-3MN132I	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	IND
LCMXO2280C-4MN132I	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	IND
LCMXO2280C-3BN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	IND
LCMXO2280C-4BN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	IND
LCMXO2280C-3FTN256I	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	IND
LCMXO2280C-4FTN256I	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	IND
LCMXO2280C-3FTN324I	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	IND
LCMXO2280C-4FTN324I	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	IND



Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	"Top View of the MachXO1200 Device" figure updated.
			"Top View of the MachXO640 Device" figure updated.
			"Top View of the MachXO256 Device" figure updated.
			"Slice Diagram" figure updated.
			Slice Signal Descriptions table updated.
			Routing section updated.
			sysCLOCK Phase Lockecd Loops (PLLs) section updated.
			PLL Diagram updated.
			PLL Signal Descriptions table updated.
			sysMEM Memory section has been updated.
			PIO Groups section has been updated.
			PIO section has been updated.
			MachXO PIO Block Diagram updated.
			Supported Input Standards table updated.
			MachXO Configuration and Programming diagram updated.
		DC and Switching Characteristics	Recommended Operating Conditions table - footnotes updated.
			MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.
		ta	Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.
			DC Electrical Characteristics, footnotes have been updated.
			Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.
			Supply Current (Standby) table and associated footnotes updated.
			Intialization Supply Current table and footnotes updated.
			Programming and Erase Flash Supply Current table and associated footnotes have been updatd.
			Register-to-Register Performance table updated (rev. A 0.19).
			MachXO External Switching Characteristics updated (rev. A 0.19).
			MachXO Internal Timing Parameters updated (rev. A 0.19).
			MachXO Family Timing Adders updated (rev. A 0.19).
			sysCLOCK Timing updated (rev. A 0.19).
			MachXO "C" Sleep Mode Timing updated (A 0.19).
			JTAG Port Timing Specification updated (rev. A 0.19).
			Test Fixture Required Components table updated.
		Pinout Information	Signal Descriptions have been updated.
			Pin Information Summary has been updated. Footnote has been added.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connections have been updated (PCLKTx_x> PCLKx_x)
		Ordering Information	Removed "4W" references.
			Added 256-ftBGA Ordering Part Numbers for MachXO640.
May 2006	02.1	Pinout Information	Removed [LOC][0]_PLL_RST from Signal Description table.
			PCLK footnote has been added to all appropriate pins.
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.